

3" WAFER SCRIBER/BREAKER



The Scribe 100 is an unique machine designed scribing & breaking of delicate die, such GaAs & silicon chip. Very flexible and uses the scribe and break sequence that keeps the finished die clean and free from damage. During the breaking mode, the scribe 100 uses the Mylar film to hold the die as the linear knife is raised to break along the core line. The film prevents contamination or stress to the die. All parameters are set from the control key boards, the machine is robust, vibration free and requires minimal training to operate.

SCRIBING HEAD

- Z motion with adjustable angle
- Adjustable scribing force from 3gr up to 50gr; constant weight
- Diamond Tool: Adjustable for angle & rotation
- Tool Offset with cross-hair

WAFER TABLE

- Wafer chuck till 3"
- Die Size: Minimum 200µm square up to 10mmx10mm
- Wafer thickness: 100µm and up
- Manual rotation 90 degrees
- Rotation alignment by micrometric screw
- X Y Table / resolution 1µm
- Motion control with progressive joystick weight

VISION SYSTEM

- Optics & magnification compatible with application (1 to 4x)
- Alignment: Programmable area / Manual
- TFT monitor 17" and CCD color camera high definition
- Target generator
- LED lightings

BREAKER

- Break mode: operator control or automatic
- Breaking mode: Using top Mylar surface and bottom cutter
- Mylar: removable to avoid contamination
- Target generator
- LED lightings

PARAMETERS

- Step Index
- Y scribe speed from 0.1 to 20 mm/sec
- Scribing length programmable
- Repeat scribe
- Number of scribe
- Component number
- Touchdown speed
- Cutter speed

TECHNICAL SPECIFICATION

Power:	100 / 230VAC 50watt
Air:	70psi
Vacuum:	60%
Dimensions:	450x700x500mm (18"x28"x20")
Weight:	80kgr.

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